先進垂直連續酸性電鍍銅技術

Advanced Solution for Vertical-in-Line Equipment

COPPER GLEAM™ HV-101 Acid Copper
COPPER GLEAM™ HV-606 Acid Copper

HV-101 exhibits excellent plating performance and advantage for production. High plating efficiency helps to increase productivity and reduce plating cost.

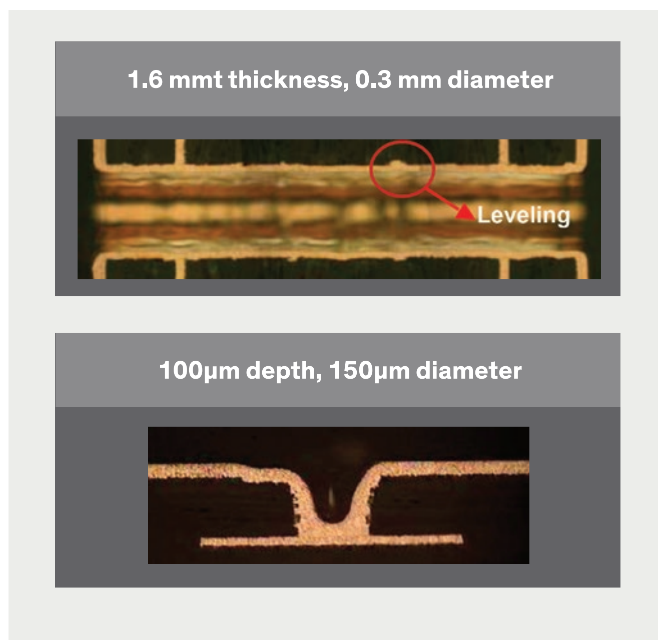
HV-606 is developed from the basis of HV-101 for insoluble anode plating system, which provides similar performance but higher operation current density.

HV-101具備優越的電鍍特性與量產的優勢。高電鍍效率有助於提高產能並減少電鍍成本。

HV-606 為基於HV-101的基礎所發展出來的產品，應用於不溶解性陽極的電鍍系統。HV-606的優越表現接近HV-101，差別在於HV-606可操作於較高的電流密度。

Advantage of HV-101 and HV-606:
HV-101和HV-606具備以下優越的特性：

- Excellent Throwing Power on Through Hole and Microvia over High Current Density
  在高電流下仍具備優異的通孔與盲孔貫孔能力
- Superior Panel Plating Distribution
  良好的電鍍均勻度
- Superior Leveling Effect to both Copper Layer on Board Surface and Hole Wall in Through Hole
  於表面與孔內有良好的整平效果
- Round Bottom Phenomenon on Microvia
  於盲孔底部有圓孔效果
- Good Thermal Reliability
  卓越的耐熱信賴度



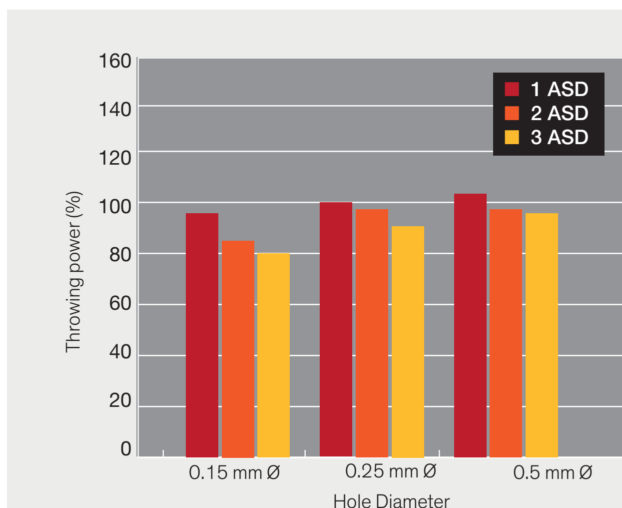


Figure 1. TP performance on different through hole diameter and current density

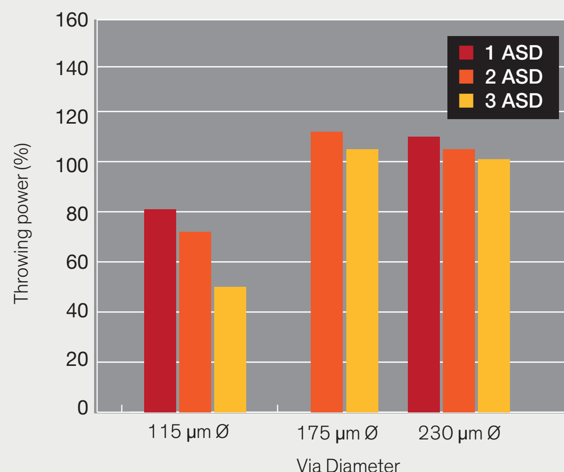


Figure 2. TP performance on different microvia diameter and current density

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